

009060" 27195960

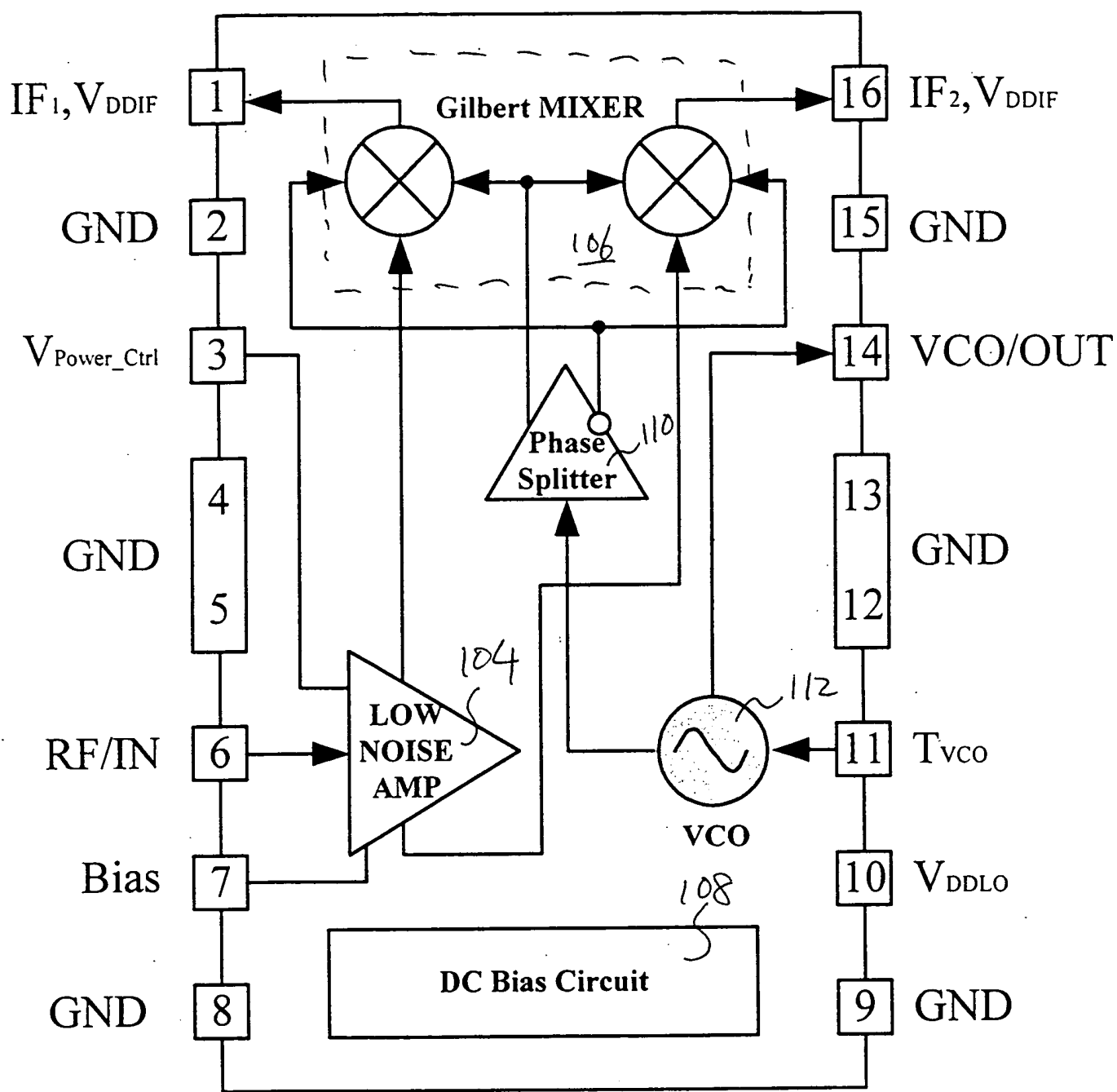


Fig. 1

PRIOR ART

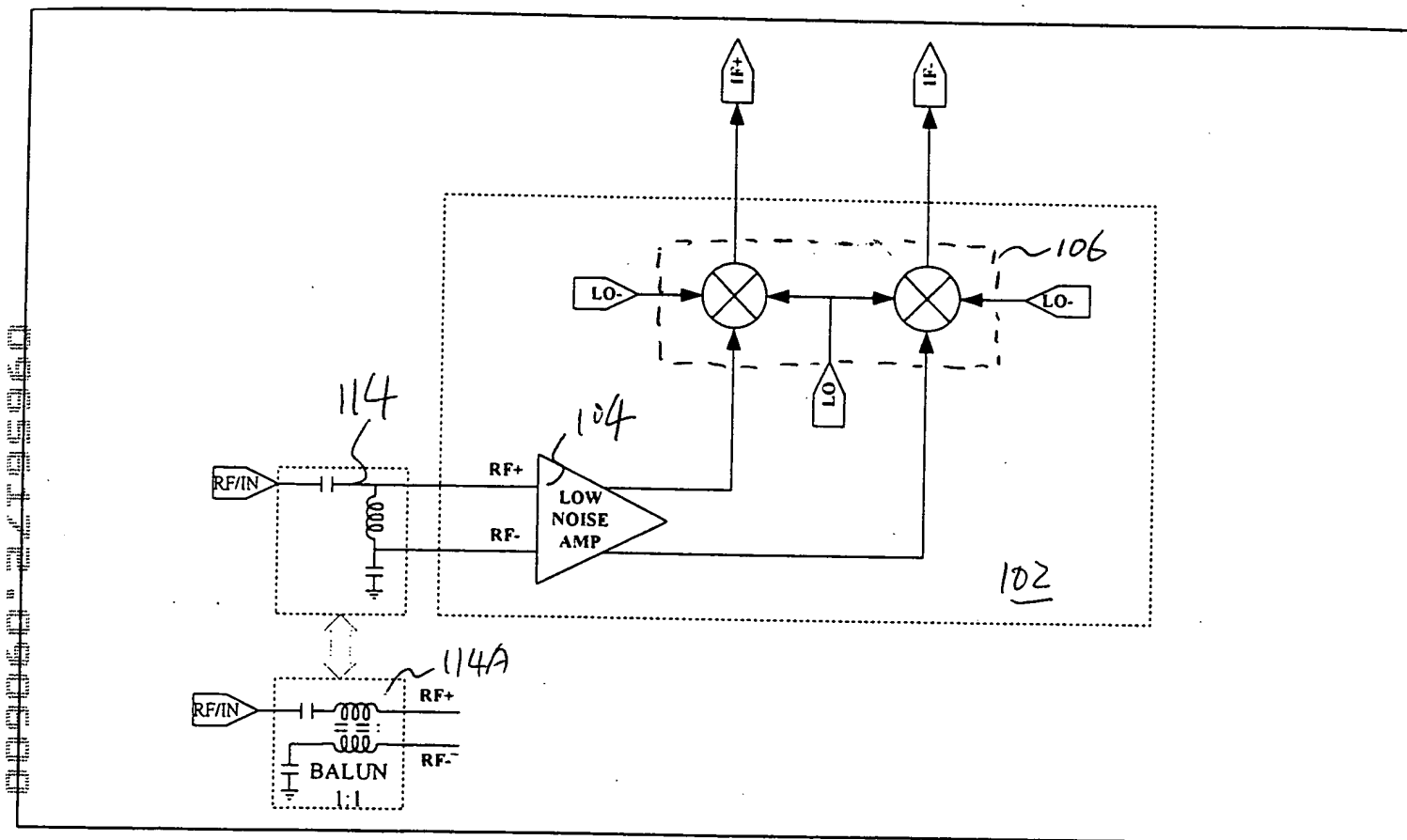


Fig. 2

PRIOR ART



Fig. 3
PRIOR ART

005050" 27T95950

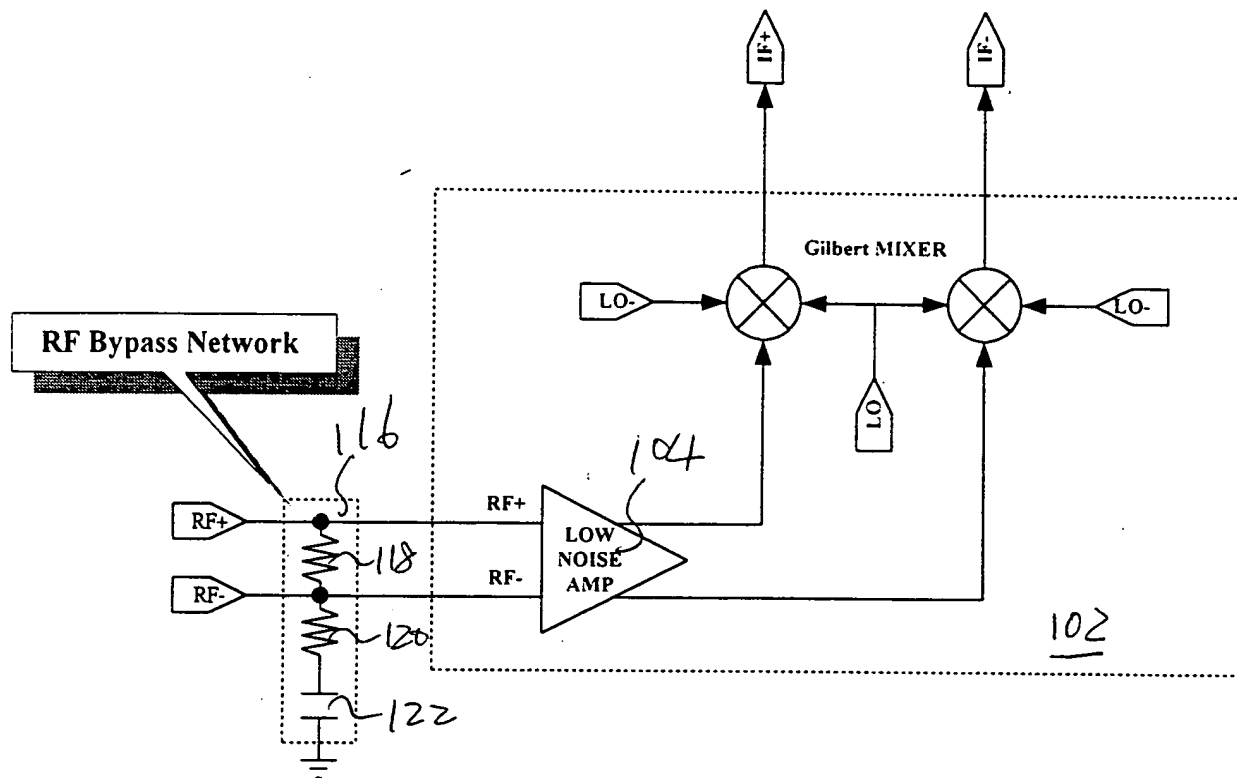


Fig. 4
PRIOR ART

09656172-090600

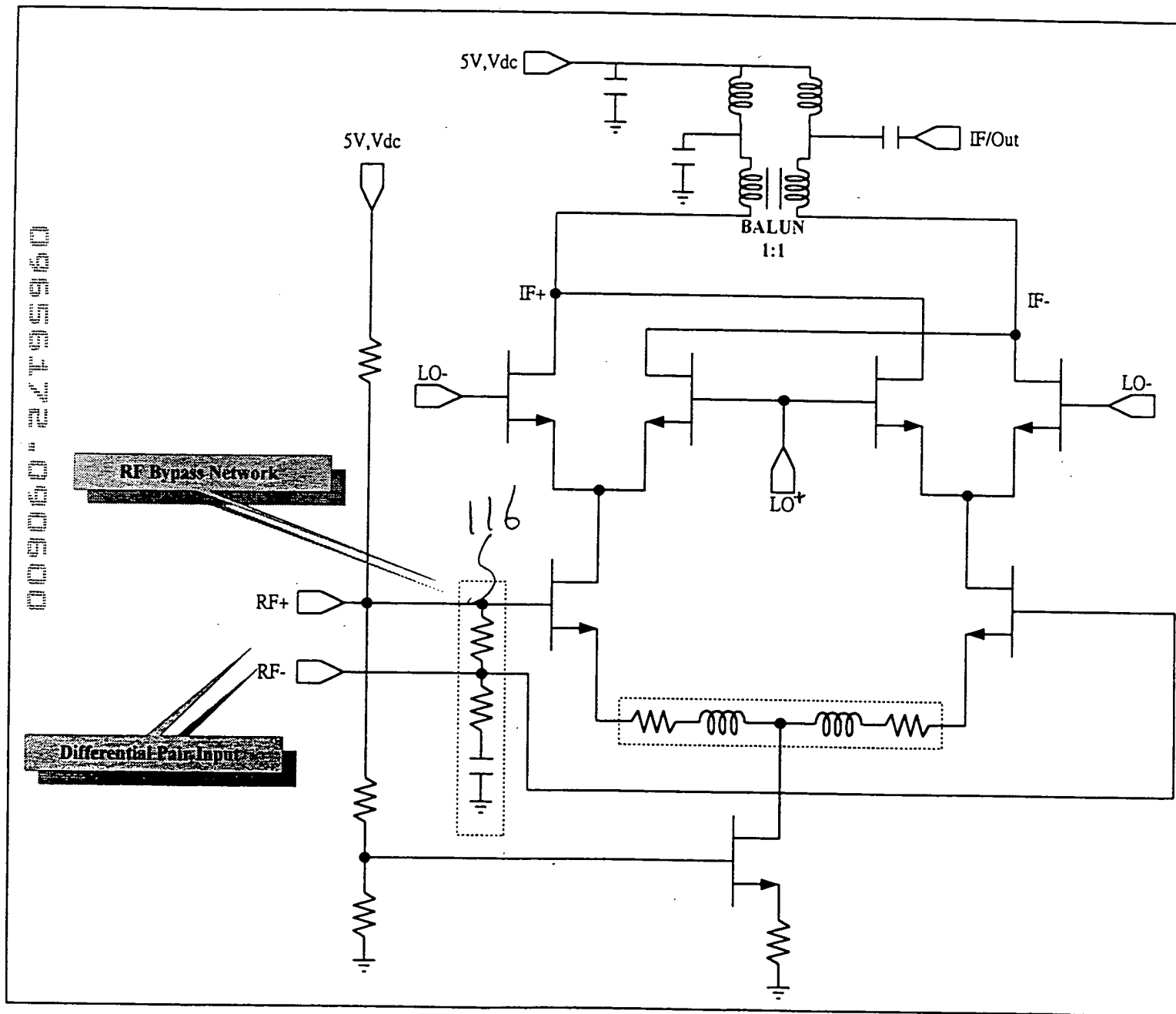


Fig. 5
PRIOR ART

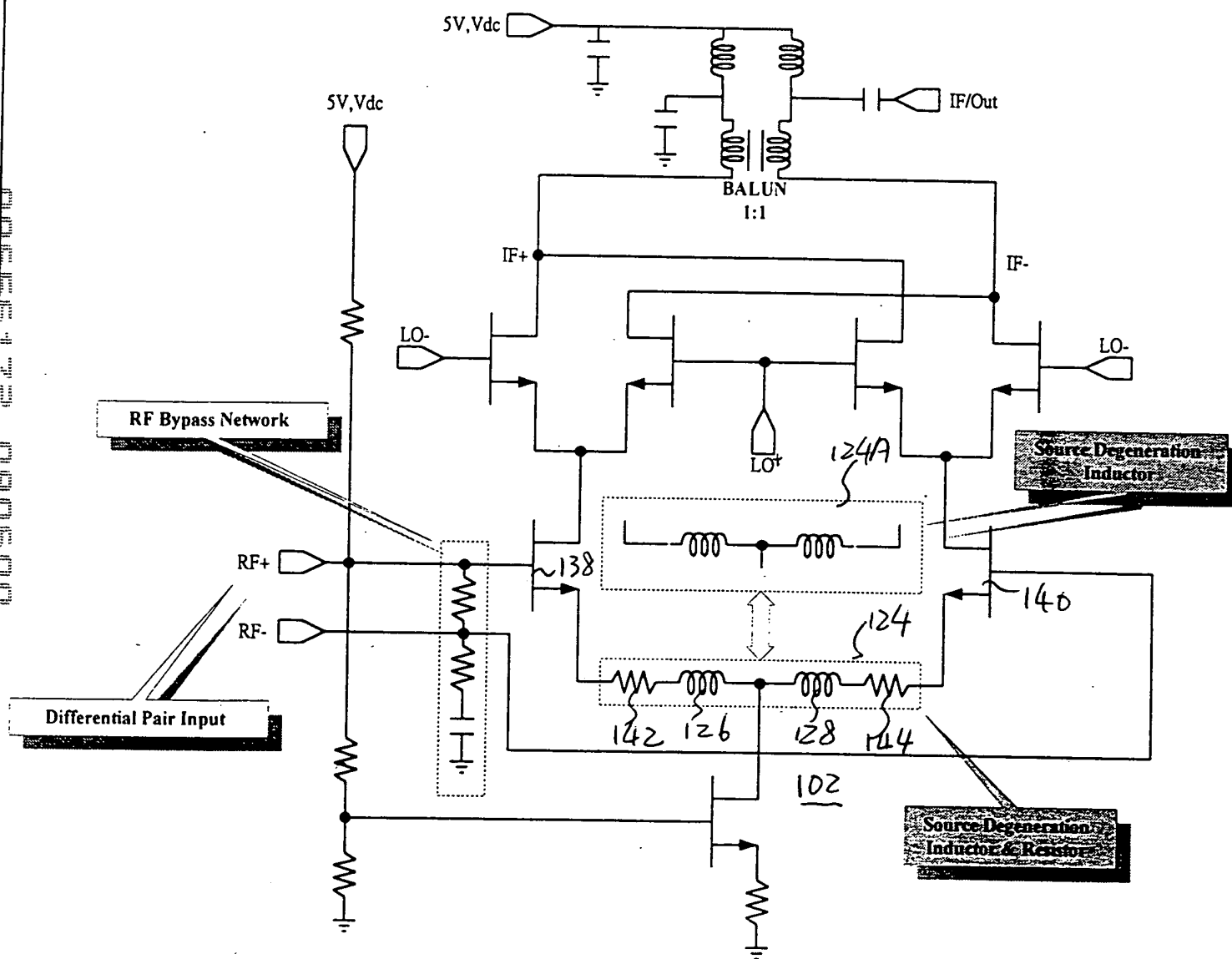


Fig. 6
PRIOR ART

009060" 22795960

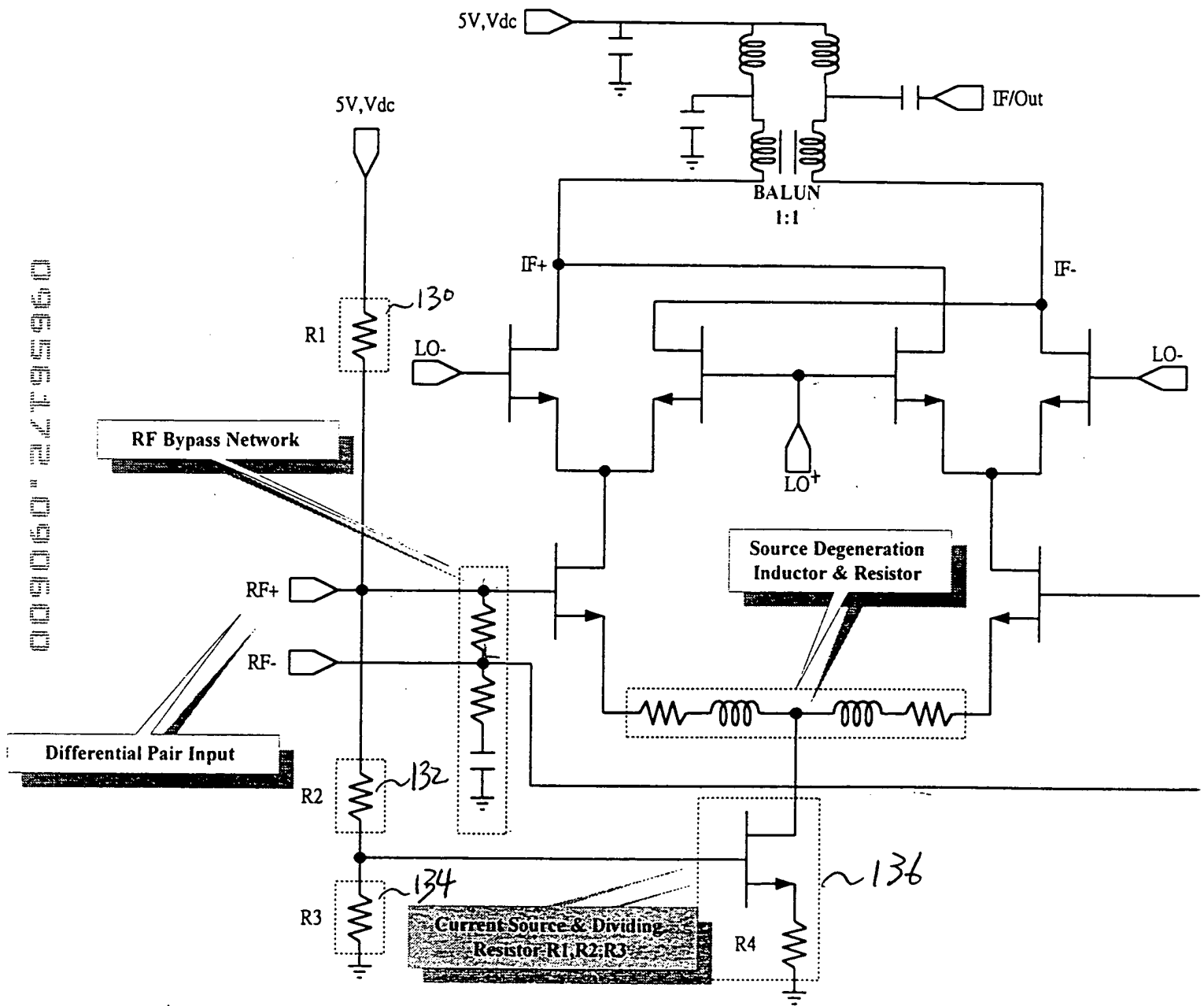


Fig. 7
PRIOR ART

009060-279960

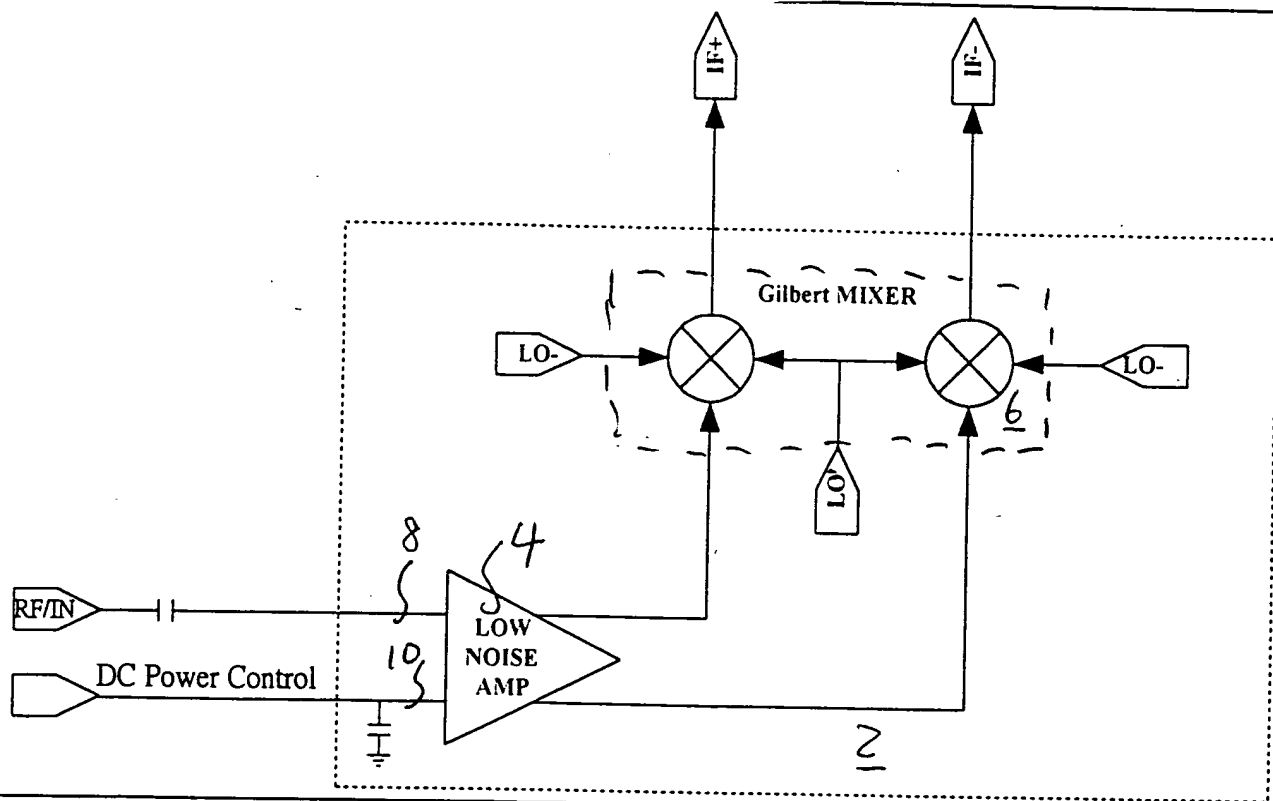


Fig. 8

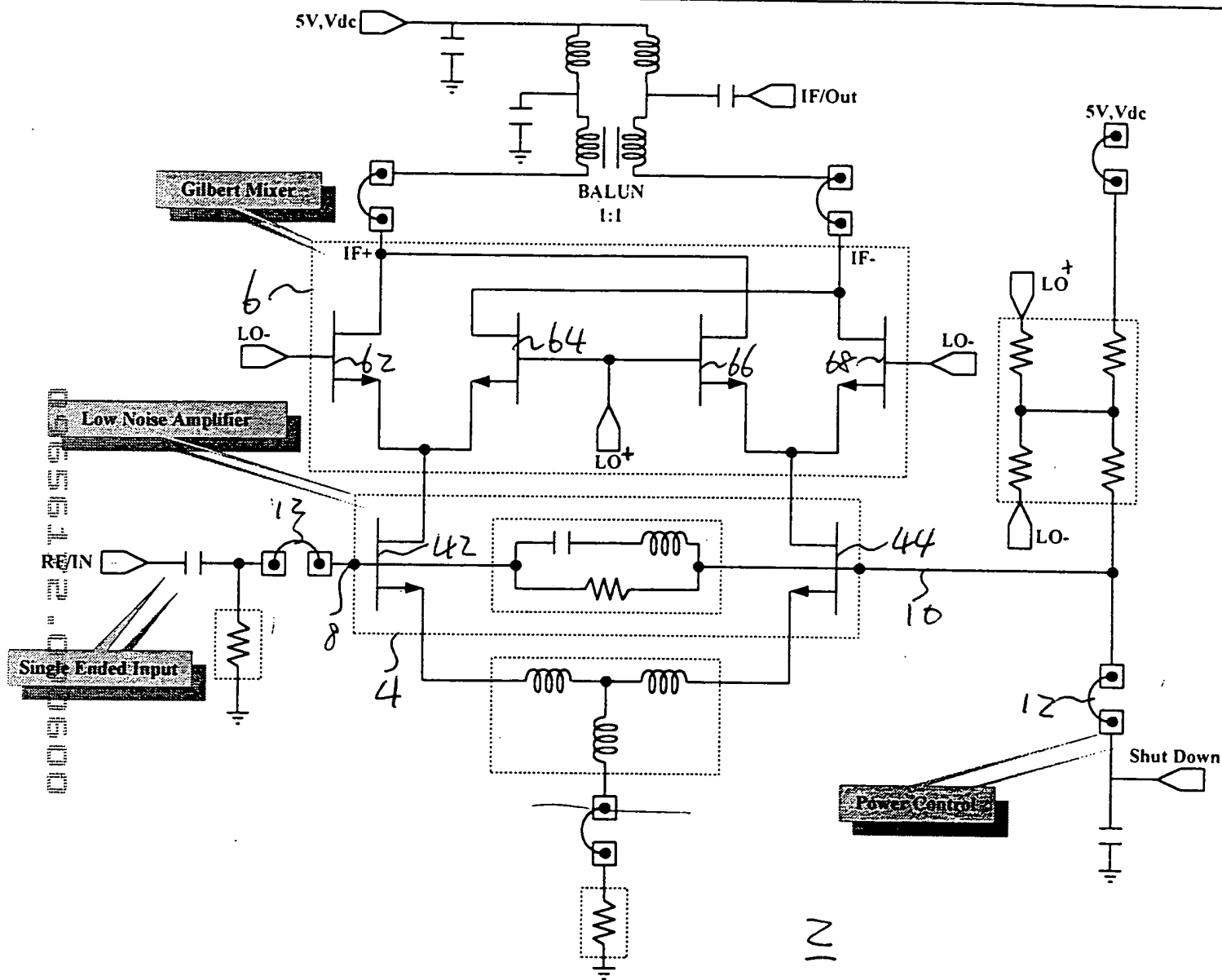


Fig. 9

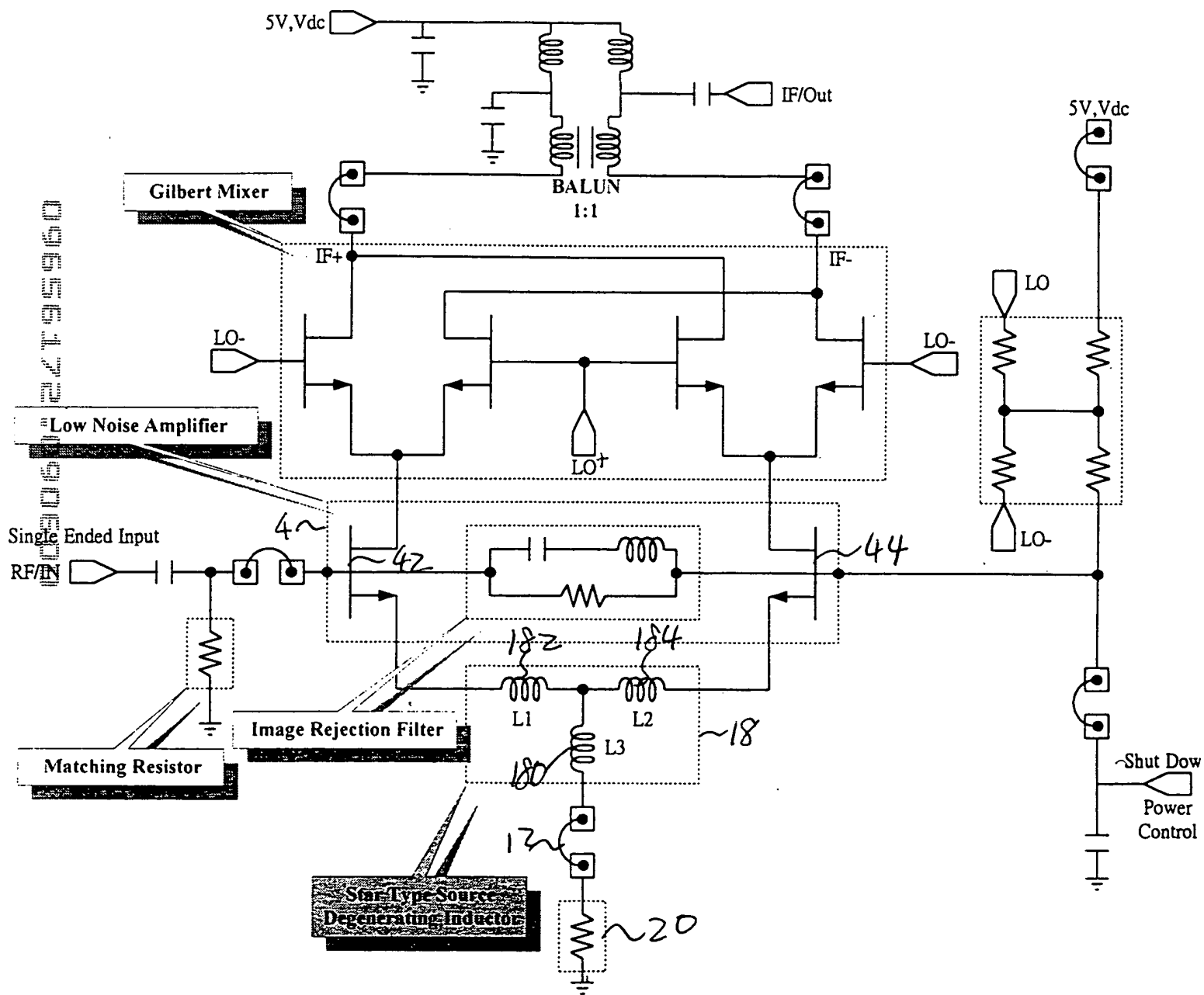


Fig. 11

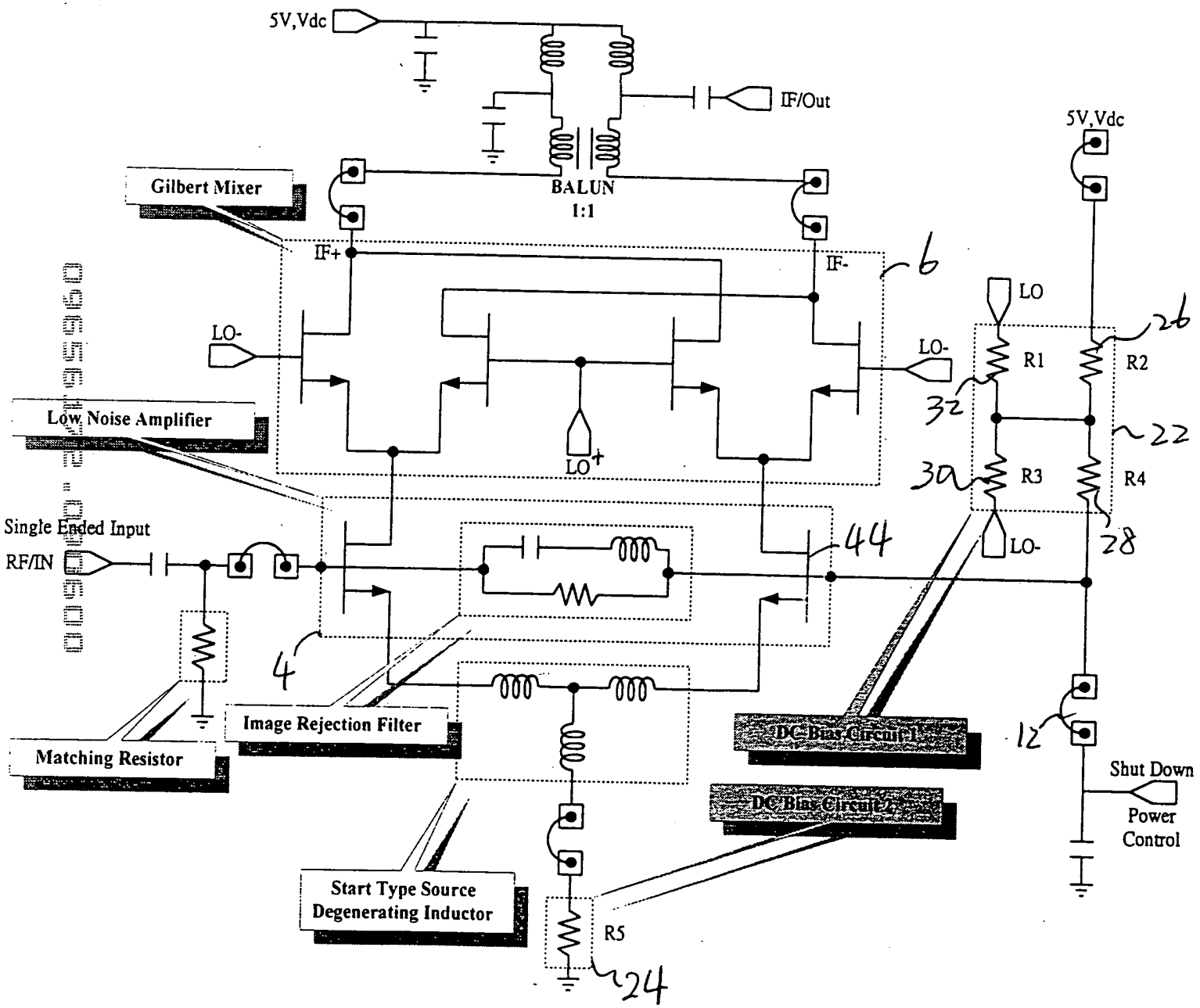


Fig. 12

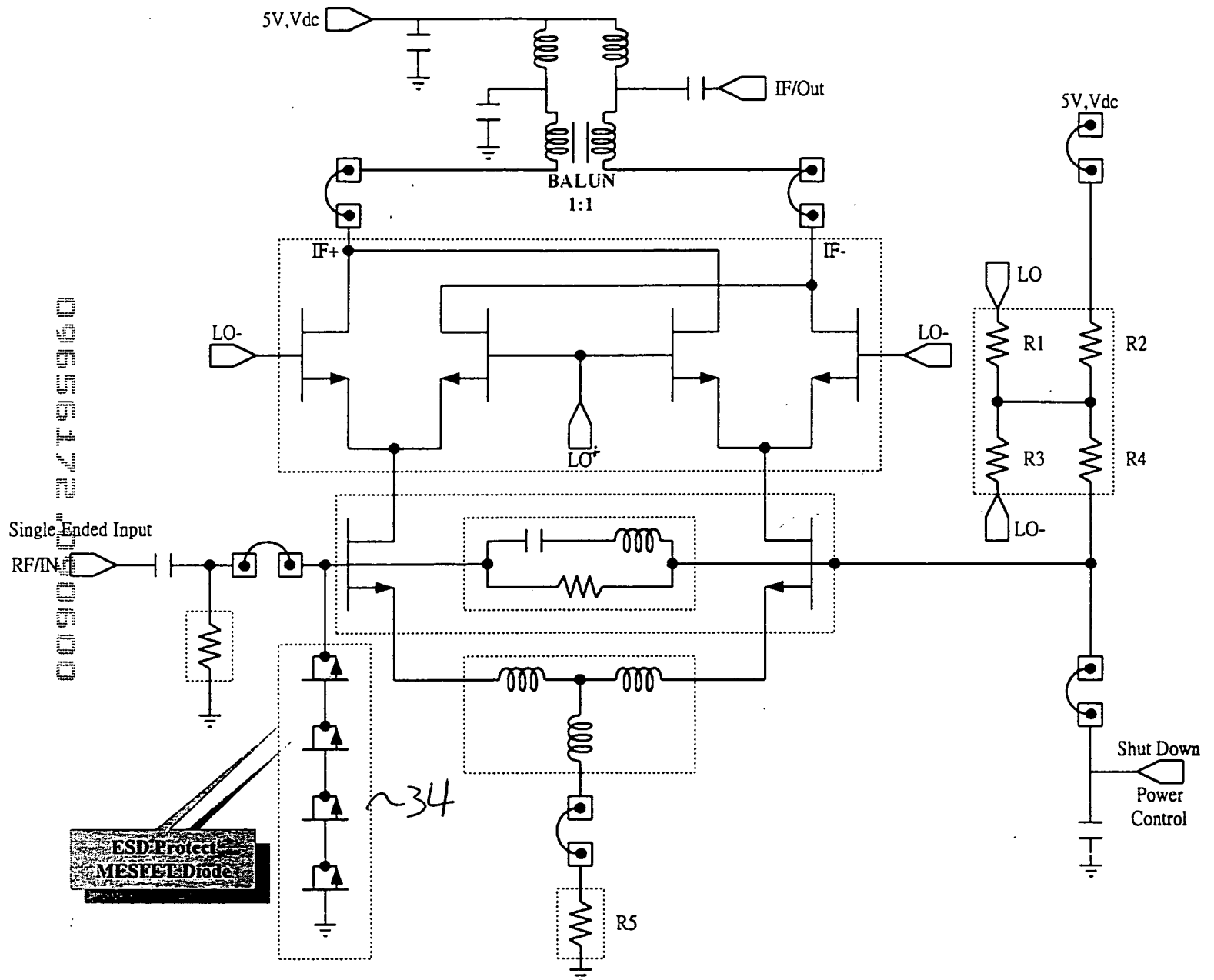


Fig. 13

The schematic diagram illustrates a semiconductor device 36, which includes a central chip 38 mounted on a leadframe. The chip 38 is connected to various pins and components:

- Top Pins:** IF₁, V_{DDIF}; GND; V_{Power_Ctrl}; GND; IF₂, V_{DDIF}; GND; VCO/OUT.
- Bottom Pins:** RF/IN; Bias; GND; V_{DDL0}; GND.

Internal components on the chip 38 include:

- Two diodes (circles with an 'X') at the top.
- A large triangle pointing upwards in the center.
- A circle with a tilde (~) on the right side.
- A rectangular block at the bottom.

The leadframe is labeled "Leadframe" and "GND". A dashed box 36 encloses the bottom right portion of the device, showing a circuit with a capacitor, a diode, a resistor, and a battery symbol.

40 Fig. 14